

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1049	438/618.ccls.	US-PGPUB; USPAT	OR	OFF	2005/02/17 09:53
S2	10675	"liquid metal"	US-PGPUB; USPAT	OR	OFF	2005/02/17 09:54
S3	4	S1 and S2	US-PGPUB; USPAT	OR	OFF	2005/02/17 09:54
S4	1250769	@ad>"20000425"	US-PGPUB; USPAT	OR	OFF	2005/02/17 09:54
S5	1250820	@ad>"20000425" or @rlad>"20000425"	US-PGPUB; USPAT	OR	OFF	2005/02/17 09:56
S6	1049	438/618.ccls.	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:27
S7	10675	"liquid metal"	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:07
S8	4	S6 and S7	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:07
S9	1250820	@ad>"20000425" or @rlad>"20000425"	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:07
S10	2	S8 not S9	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:07
S11	963	438/672.ccls.	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:31
S12	4	S7 and S11	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:28
S13	2	S12 not S9	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:28
S14	89670	"438"/\$.ccls.	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:28
S15	611	438/675.ccls.	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:31
S16	1	S7 and S15	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:31
S17	1	S16 not S9	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:31
S18	197	438/642.ccls.	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:31
S19	2	S7 and S18	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:32
S20	1	S19 not S9	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:32
S21	279	S7 and S14	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:33
S22	141	S21 not S9	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:34

S23	331003	solder or pad	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:34
S24	28	S22 and S23	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:56
S25	1	("6627993").PN.	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:41
S26	5	("4552691"   "5275330"   "5414221"   "5796591"   "6171944").PN. OR ("6627993"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2005/02/17 11:48
S27	0	"solder pad" and "liquid metal"	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 11:49
S28	9742	"liquid metal"	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 11:49
S29	174966	pad	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 11:49
S30	66	S28 and S29	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 11:49
S31	1111392	semiconductor or "integrated circuit"	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 11:50
S32	12	S30 and S31	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/17 11:52
S33	1800	"metal paste"	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:55
S34	1	S11 and S33	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:55
S35	0	S34 not S9	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:55
S36	2	S15 and S33	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:55
S37	1	S36 not S9	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:56
S38	0	S18 and S33	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:56
S39	232	S14 and S33	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:56
S40	98	S39 not S9	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:56
S41	92	S40 not S24	US-PGPUB; USPAT	OR	OFF	2005/02/17 11:56